molex

Part Number : 877830202

Product Description : 0.60mm Pitch miniDIMM DDR Socket, Surface Mount, 22.5° Angle, 0.76µm Gold (Au) Plating, Off-White Latches, with Pick-and-Place Cap, 200 Circuits, 2.5V Voltage Key, Lead-Free

Series Number : 87783

Status : Active

Product Category : Memory Module Connectors

Documents & Resources

Drawings

Drawing 877830202_sd.pdf
Packaging Design Drawing PK-87783-002-001.pdf

3D Models and Design Files

3D Model 877830202_stp.zip
Electrical Model Document EE-87783-001-001.pdf
S-Parameter Model SP-87783-001-001.zip

Specifications

Application Specification AS-87782-001-001.pdf
Product Specification PS-87783-001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	ⓔ
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Memory Module Connectors
Series	87783
Description	0.60mm Pitch miniDIMM DDR Socket, Surface Mount, 22.5° Angle, 0.76µm Gold (Au) Plating, Off-White Latches, with Pick-and-Place Cap, 200 Circuits, 2.5V Voltage Key, Lead-Free
Component Type	Socket
JEDEC Outline	MO-258
Product Family	MiniDIMM Sockets
Product Name	MiniDIMM
UPC	822350075121

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	2.5V
Voltage - Maximum	30V

Physical

Circuits (Loaded)	200
Circuits (maximum)	200
Durability (mating cycles max)	25

Entry Angle	22.5° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	5.444/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
Pitch - Mating Interface	0.60mm
Pitch - Termination Interface	0.60mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	REFLOW
Max-Cycle	2
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC MO-258 Modules
